



SCIENTECH

# 辛耘

許明棋 2025/06/17

- 本簡報可能包含對於未來展望的表述。該類表述是基於對現況的預期，但同時又受限於已知或未知的風險與不確定性的影響。因此實際結果將可能不同於表述內容。
- 除法令要求外，公司並無義務因應新資訊的產生或未來事件的發生，主動更新對未來展望的表述。



# 公司簡介

Overview | Milestones | Location | Certificate | Competence





## Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative



## Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)



**Established:**  
**1979**  
**Taipei, Taiwan**

**Capital:**  
**US\$ 27 Million**  
**TWSE:3583**

**Employees:**  
**>1020**  
**(Worldwide)**

## Over 1020 Staffs

### Representative

- 140 in Taiwan
- 130 in China
- 70% in Service and Process Support

### Equipment Design and Maf'g

- 350 in Total
- 100+ in R&D, Process and Design

### Wafer Reclaim

- 315 in Total

### Administration

- 85 in Total



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**1979**



**1985**

Branch Office  
in Hsinchu, Taiwan

**1995**

Subsidiary  
in CA, USA

**2001**

Subsidiary  
in Shanghai, China

**2002**

Singapore

**2003**

Equipment Manufacture  
Department Established

**2021**

Subsidiary  
in Villach, Austria

**2019**

Over 500 Equipment  
Sales Achievement

**2013**

Publicly Listed in  
Taiwan Stock Market

**2007**

New Factory  
in Hukou Opened

**2006**

Wafer Reclaim  
Business Launched

**2004**

New Hsinchu  
Office Opened



Taipei Headquarter

HsinChu Office

HuKou Factory

- Equipment Design and Manufacturing
  - ◆ Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim



Taichung Office

Kaohsiung Office

Tainan Office



## Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

## USA

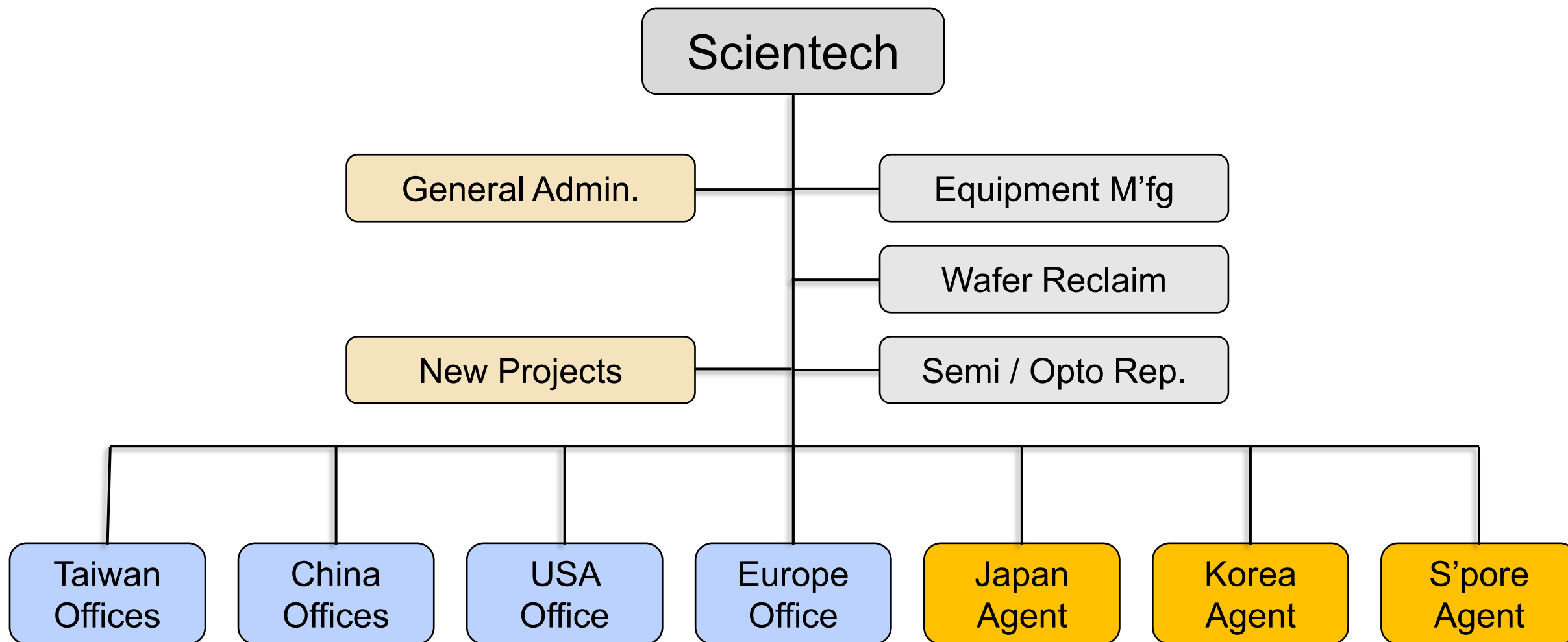
Santa Clara, CA (1994)

- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

## China

- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

# 辛耘公司組織架構



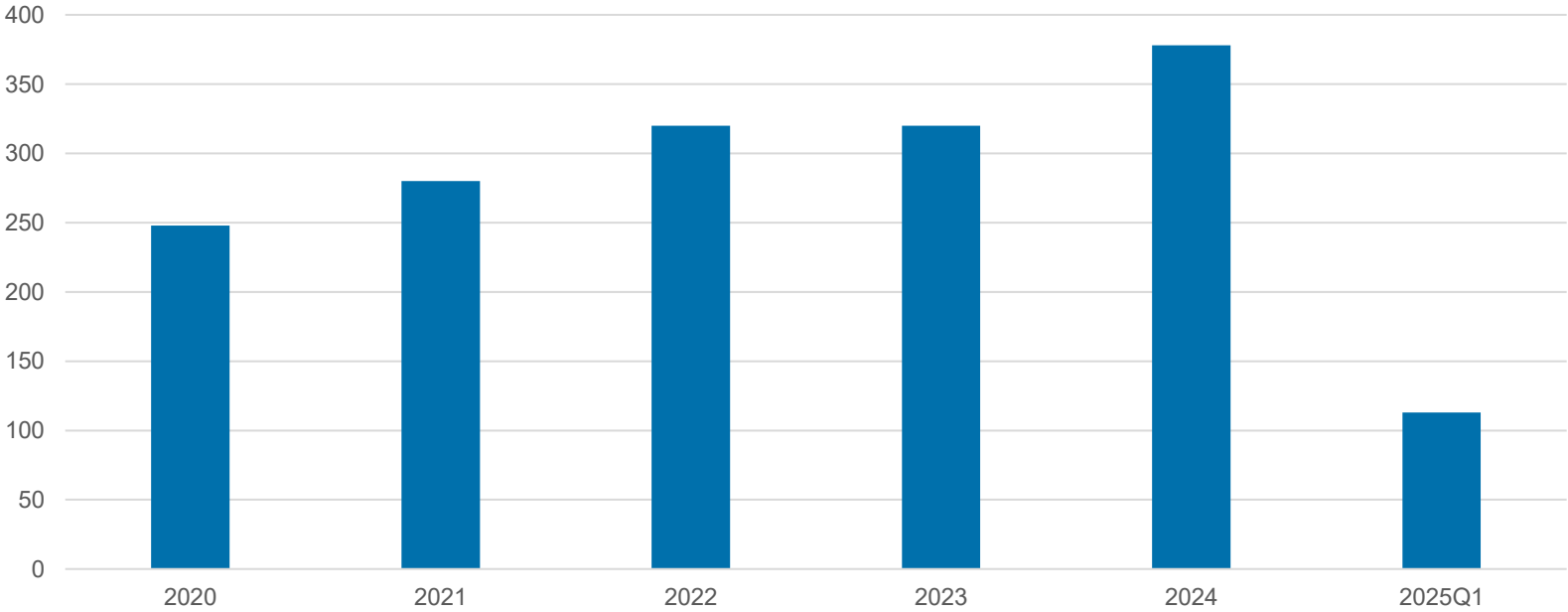
# 產品與服務

Wafer Reclaim | Equipment Manufacturing and Design |  
Representative

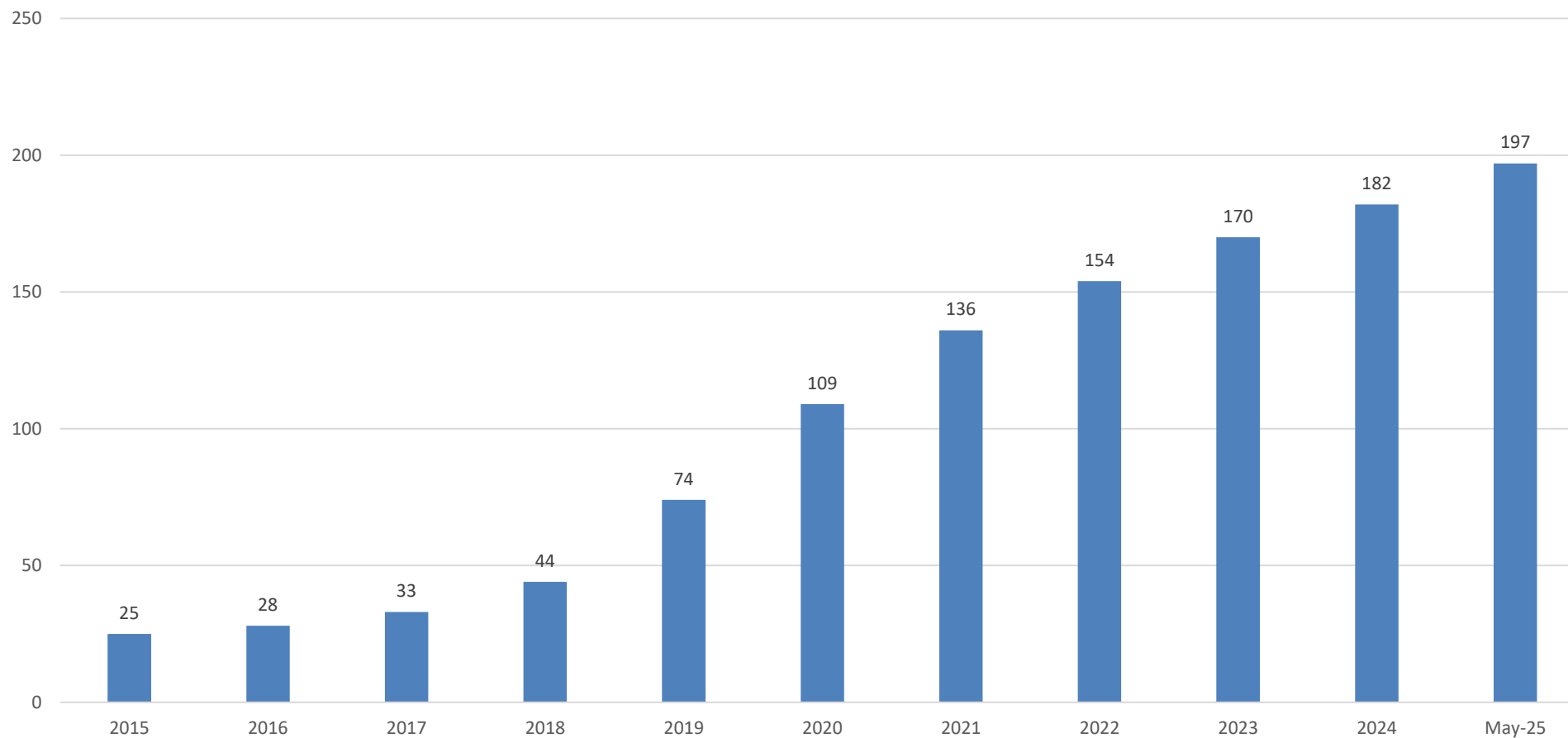


| 單位：百萬           | 2020 | 2021  | 2022  | 2023  | 2024  | 2025Q1 |
|-----------------|------|-------|-------|-------|-------|--------|
| 研發費用            | 248  | 280   | 320   | 341   | 378   | 113    |
| 研發費用佔<br>營業收入比重 | 6.9% | 6.0%  | 5.7%  | 4.9%  | 3.9%  | 4.0%   |
| 研發費用佔<br>製造比重   |      | 14.9% | 15.3% | 15.7% | 11.3% | 10.8%  |

R&D Expenses



- The cumulative number of patents on file is 197, and 52 applications are pending.





## Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...



## Wafer Reclaim

- 12" Si Wafer



## Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

## Advanced Clean Technology

- 19nm Particle
- Low Trace Metal (<1E9)



## Advanced Defect Inspection (SP1/SP2/SP5/SP7)



## 12" Si Wafer

- Capacity: 160K / Month
- Cu and Non-Cu Process



*Cleaning*

*Etching*

**Full Process  
Optimization**



## Capacity Expansion

- Additional 50K / Month by end of 2025



*Polishing*

*Grinding*

## Complete Polishing Process

- Single/Double Side Polish
- Final Haze Polish

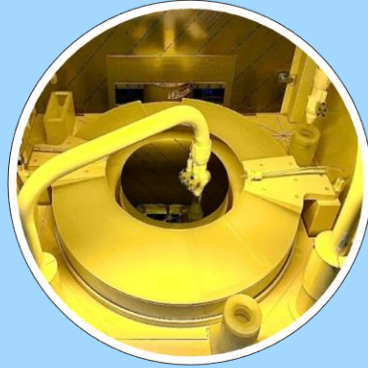


## Super Flatness (GBIR < 0.5mm)





**Wet Bench**



**Single Wafer**



**TBDB**



**Baking**

## 批次式濕式製程設備

### Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping...

### Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

### Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au



## 單晶圓濕式製程設備

### Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

### Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

### Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean



## 暫時性貼合及剝離設備(TBDB)

### Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

### Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

### Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling



## 水氣烘烤設備



### Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor



### Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake



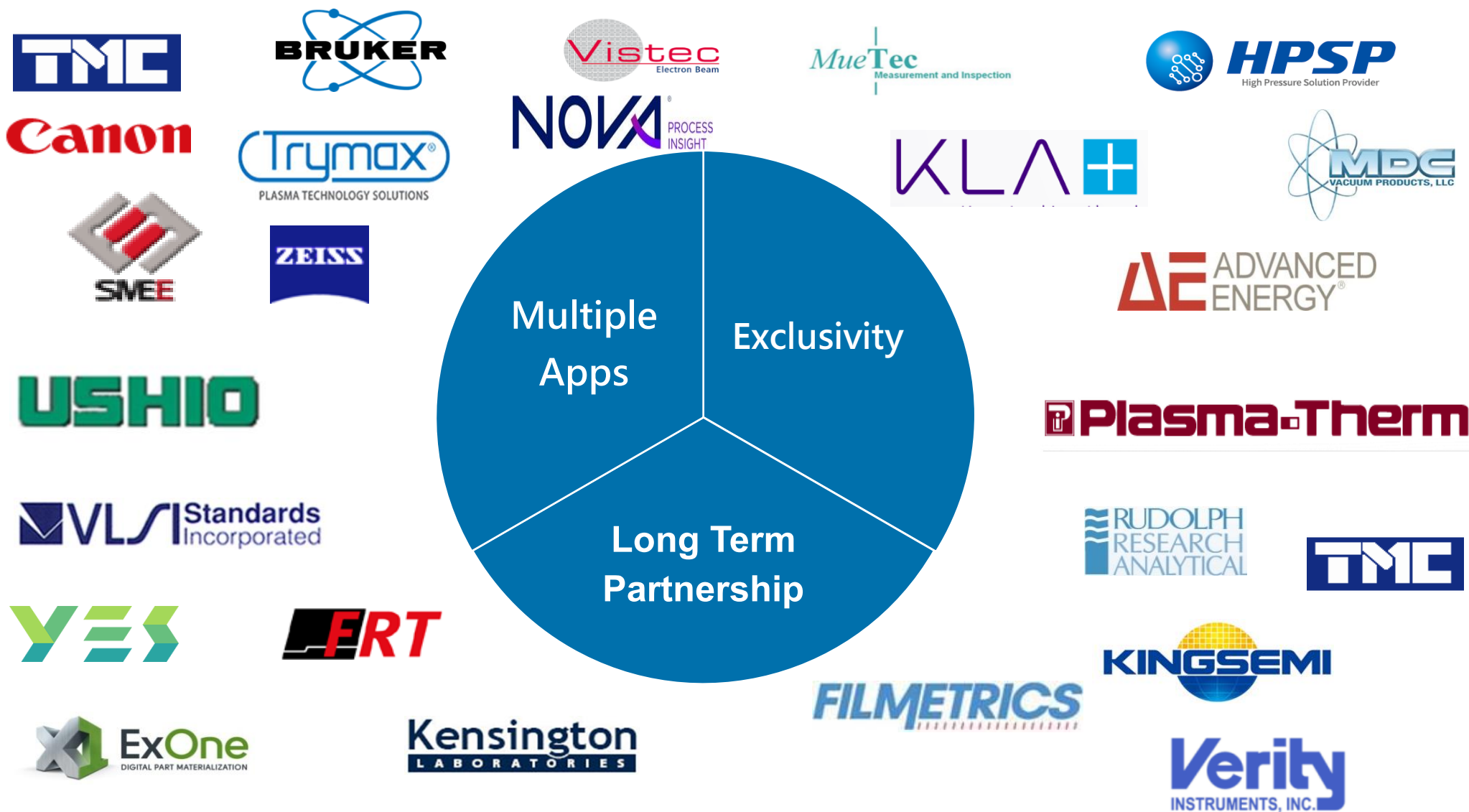
### Features

- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot





# 代理事業

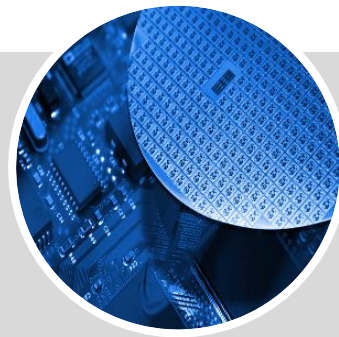




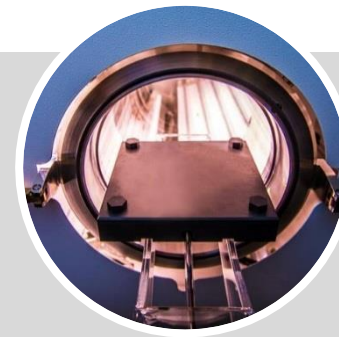
Lithography



Etch



Thin Film



Diffusion







## Metrology



## Sub-Systems



## Package & Material



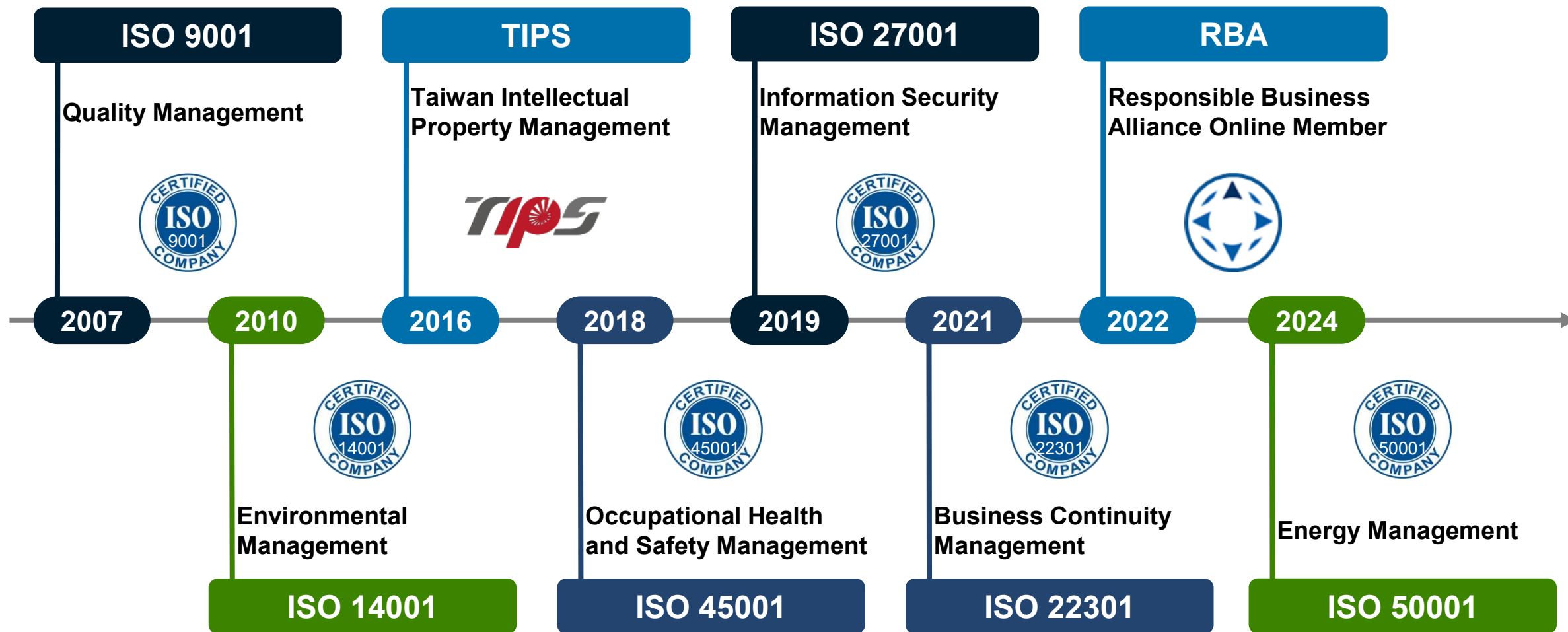
## Robot Repair and Refurbish



# 公司治理

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## 發行永續報告書



E



環境友善

S



溫馨職場



回饋社會

G



誠信經營



**SEMICON<sup>®</sup>**

**Semicon China**

Mar. 26-28, 2025  
Shanghai



**SEMICON<sup>®</sup>**

**Semicon TW**

Sep. 10-12, 2025  
Taipei



**SEMICON<sup>®</sup>**

**Semicon West**

Oct. 07–09, 2025  
Phoenix



**SEMICON<sup>®</sup>**

**Semicon Europa**

Nov. 18-21, 2025  
Munich



**ISES**

May 13-14, 2025  
Taipei



**ECTC**

May 27-30, 2025  
Dallas, Texas



# 營運概況

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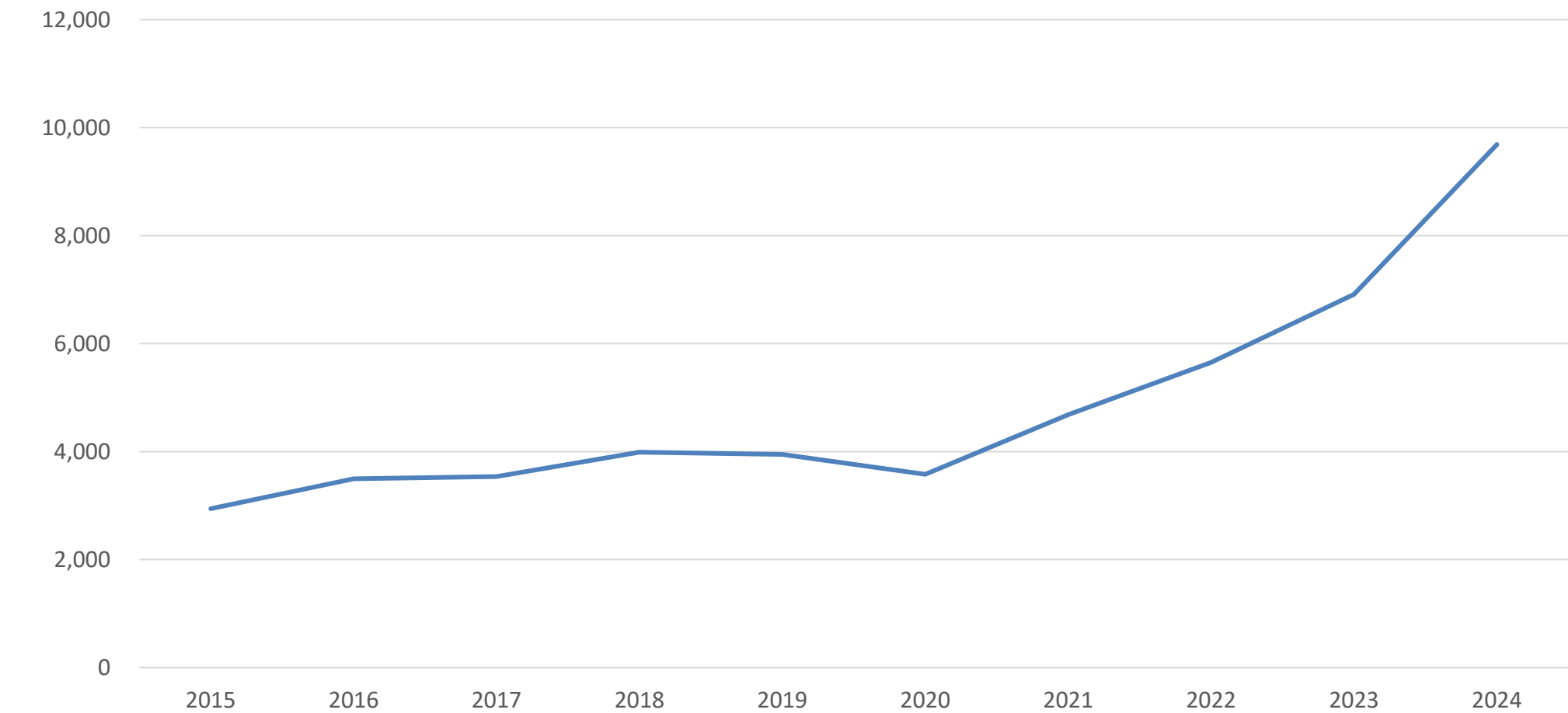
# 簡明損益表

| Units : NT \$ M          | 2020               | 2021               | 2022               | 2023               | 2024                | 2025Q1             |
|--------------------------|--------------------|--------------------|--------------------|--------------------|---------------------|--------------------|
| Revenues                 | 3,580              | 4,684              | 5,650              | 6,911              | 9,688               | 2,812              |
| Gross Profit             | 1,456              | 1,667              | 2,084              | 2,201              | 2,906               | 893                |
| Operating Expenses       | 991                | 1,112              | 1,374              | 1,483              | 1,790               | 545                |
| Operating Income         | 465                | 555                | 710                | 718                | 1116                | 349                |
| Income Before Tax        | 389                | 524                | 736                | 860                | 1277                | 367                |
| Net Income               | 305                | 420                | 568                | 650                | 927                 | 257                |
| <b>EPS</b>               | <b><u>3.80</u></b> | <b><u>5.23</u></b> | <b><u>7.08</u></b> | <b><u>8.10</u></b> | <b><u>11.54</u></b> | <b><u>3.20</u></b> |
| Gross Margin             | 41%                | 36%                | 37%                | 32%                | 30%                 | 32%                |
| Operating Margin         | 13%                | 12%                | 13%                | 10%                | 12%                 | 12%                |
| Income Before Tax Margin | 11%                | 11%                | 13%                | 12%                | 13%                 | 13%                |

# 歷年營收

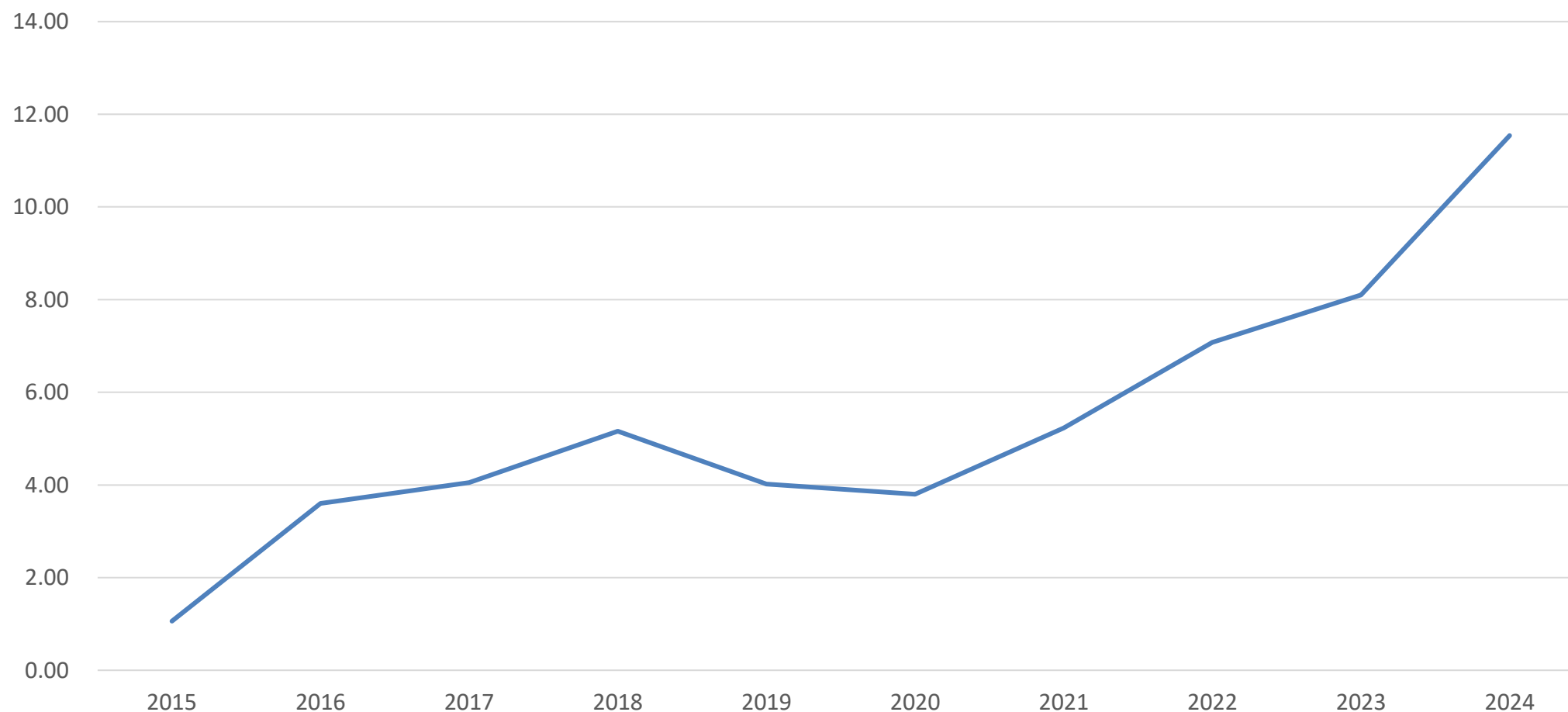


| Units<br>NT \$ M | 2015  | 2016  | 2017  | 2018  | 2019  | 2020  | 2021  | 2022  | 2023  | 2024  | 2025Q1 |
|------------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|--------|
| Revenue          | 2,942 | 3,495 | 3,539 | 3,988 | 3,949 | 3,580 | 4,684 | 5,650 | 6,911 | 9,688 | 2,813  |



# 歷年 EPS

|     | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024  | 2025Q1 |
|-----|------|------|------|------|------|------|------|------|------|-------|--------|
| EPS | 1.06 | 3.6  | 4.05 | 5.16 | 4.02 | 3.8  | 5.23 | 7.08 | 8.1  | 11.54 | 3.20   |



# 未來展望

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- The CAGR of the Semi. market size over the next 10 years is approximately **8%**
- In 2025, the global Semi. market is expected to grow **11%**
- Driven by demand in artificial intelligence (AI) and high-performance computing applications, the semi. market in Taiwan:

| Year | Market Size<br>(Billion US\$) | Growth Rate<br>(%) |
|------|-------------------------------|--------------------|
| 2024 | 165                           | 22                 |
| 2025 | 187                           | 16.5               |

- 12-inch semi. advanced process continues to thrive
  - **Front-End:** 5nm 、 3nm 、 2nm 、 1nm
  - **Advanced Package:** Fan-Out 、 2.5D (CoWoS) 、 3D (SoIC)...etc



- The CAGR of Advanced Packaging over the next 10 years is estimated at **11%**.
- **CoWoS** production capacity is expanding substantially to meet the rising demand for AI chip applications
- AI applications are expanding from data centers to **personal devices**
- **China's** semi. production capacity is expanding, intensifying price competition in mature process nodes.
- **Compound Semi:**
  - Investment in electric vehicles (**EVs**) and **5G** is stagnant
  - Mobile phone demand is saturating, leading to reduced **GaAs** production
  - **SiC** demand gradually increases, with new capacities slowing down
  - **Micro LED** adoption is progressing slowly

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q4: 9,000 M-Square new building (Plant II) for equipment manufacturing, and warehouse next to Hukou Plant (Plant I)**
- **2026 Q4: Wafer Reclaim Capacity 30K/Month at Hukou Plant**
- **2027 Q1: 20,000 M-Square new building for equipment manufacturing, and warehouse in Tainan (southern Taiwan)**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant



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Thank You!

<https://www.scientech.com.tw>